Treating method for protecting devices on wafer

ABSTRACT

The present invention secures protection of devices formed on a wafer from contamination throughout a period of time from the beginning of a back grind step of the wafer to the completion of dicing. To a wafer surface on which devices are provided (1), a coating material is applied to form a coating film (2), a BG tape for back grind is attached thereon (3), the wafer surface side is fixed, and the wafer backside is subjected to grinding to conduct thinning of the wafer (4). Then, the wafer backside is fixed to a dicing tape whose rear side is provided on a wafer frame (5), and then the BG tape is peeled away (6), a diving process is conducted to cut the wafer into respective devices (7), and the coating film covering the surface of the devices throughout the period of time until the completion of these steps is removed by washing (8).

Fig. 1